

Storage and Process Instructions:

For parts exposed to greater than 60% RH, it is recommended parts be baked at 125°C for 3-5 hours prior to SMT reflow process. If unsure of RH exposure, it is recommend to bake at the above temperature and time prior to SMT reflow process.

SPECIFICATIONS:

ELECTRICAL:

RATED CURRENT: 5A RATED VOLTAGE: 300VDC

WITHSTANDING VOLTAGE:

500VAC (rms) FOR 1 MIN INSULATION RESISTANCE: > 1,000 m Ω at 500VDC CONTACT RESISTANCE: 13mOhms MAX DIELECTRIC STRENGTH: 1000VAC FOR 1 MIN

OPERATING TEMPERATURE: -55°C TO +105°C

MATERIALS:

SHELL: BRACKET:

NICKEL PLATED STEEL NICKEL PLATED STEEL INSULATOR: NYLON 6T, UL 94V-0, BLACK

PROCESS TEMP:

INSULATOR PATONE #322C, COLOR=Pc99 CONTACT: TIN PLATED PHOSPHOR BRONZE

GOLD FLASH MATING AREA TIN PLATED SOLDER AREA

RoHS COMPLIANT

THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF NorComp AND SHALL NOT

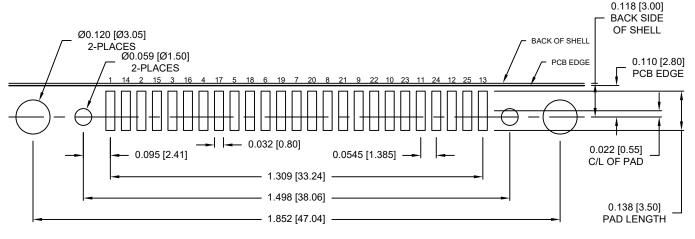
DRAWN: C. SMITH DATE: 04/14/2009

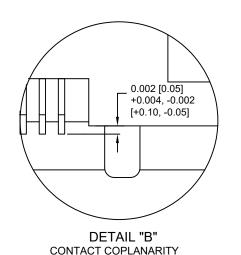
UNITS = inch [mm]

DO NOT SCALE FROM DRAWING

NorComp

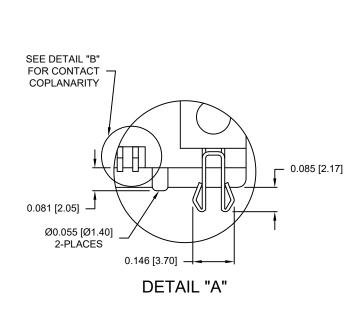
SCALE:	SHEET		OF		REV	_
NTS		1		2	12	
DWG NO.	190-025-263R001					

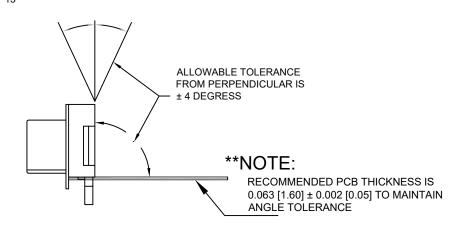




RECOMMENDED PCB LAYOUT

CONTACT ARRANGEMENT 1 14 2 15 3 16 4 17 5 18 6 19 7 20 8 21 9 22 10 23 11 24 12 25 13





ROHS COMPLIANT

M

THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF NorComp AND SHALL NOT BE REPRODUCED, COPIED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS WITHOUT WRITTEN PERMISSION.

DRAWN: C. SMITH

DATE: 04/14/2009

UNITS = inch [mm]

DO NOT SCALE FROM DRAWING

NorComp

SCALE:	SHEET		OF		RE\
NTS		2		2	1:
DWG NO.	190-0	25.	-26	3R001	